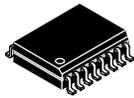


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



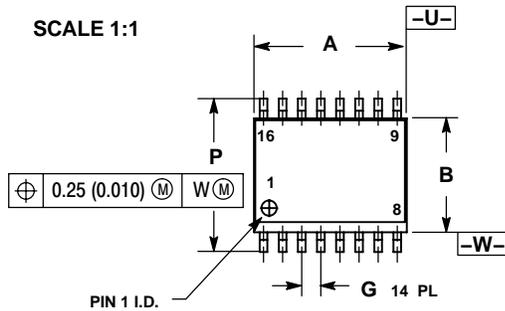
SOIC 16 LEAD WIDE BODY, EXPOSED PAD

CASE 751R-02

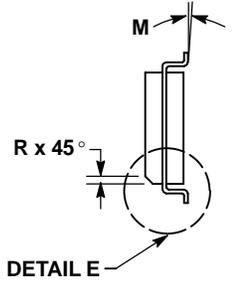
ISSUE B

DATE 18 JUL 2005

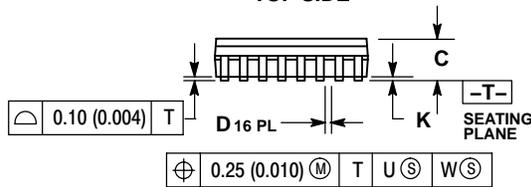
SCALE 1:1



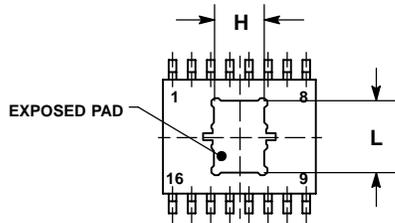
TOP SIDE



DETAIL E

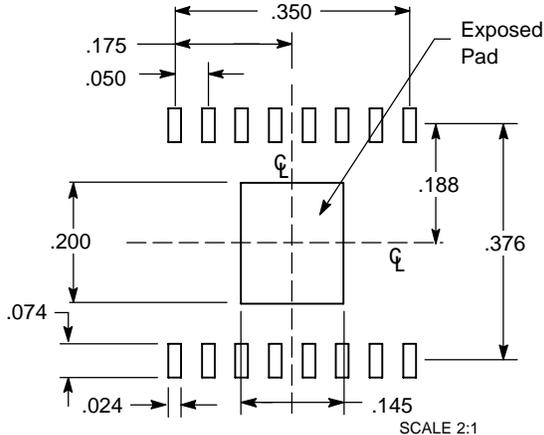


SEATING PLANE



BACK SIDE

SOLDERING FOOTPRINT*



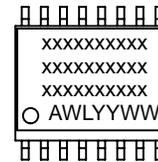
SCALE 2:1

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751R-01 OBSOLETE, NEW STANDARD 751R-02.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
H	3.31	3.51	0.130	0.138
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
L	4.58	4.78	0.180	0.188
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

MARKING DIAGRAM



- xxx = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON10370D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SOIC-16, WB EXPOSED PAD	PAGE 1 OF 2

